### SME Roundtable

Moderated by Peter Connock Board Chairman, memsstar



Organised by:

AENEAS, ARTEMIS-IA, EPoSS, ECSEL-JU &

European Commission

Associated organiser: EUREKA

SME roundtable panelists

































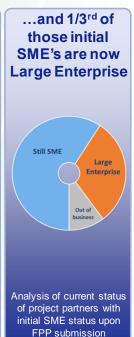
Arco Krijgsman Senior Manager Strategic Technology

# **ASML**















Alain Jarre CEO

RECIF Technologies designs, manufactures, distributes and services robotic handling equipment for highly sensitive environments dedicated to end users & OEM's of the semiconductor industry

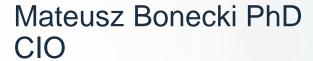
Customer orientated and pro-active, RECIF Technologies keeps a strong focus on highest product quality coupled with customer satisfaction

Acknowledged as expert in wafer handling and innovative solutions, we firmly believe that building strong partnerships with companies mastering complementary core competences, will lead us together to excellence, and better serve the industry









DAC is an IT solutions provider for mobility, transportation, and value network digitalization.

We combine expertise in IoT, data analytics, and enterprise architecture to help our clients with supply chain transparency, product traceability, and logistics optimization.







Miguel Roncales Founder and CEO AlphaSIP's main goal is to design, develop and produce molecular diagnostic chips that allow immediate and effective illness detection, promoting better health services for patients and great advances towards personalized medicine







Dr Stefan Mengel
Head of Division
"Electronics; Autonomous
Electrical Driving"
BMBF

- > Electronic Components and Systems is a priority area for Germany
- ➤ Significant funding for research over 2016-2020
  - ➤ Collaborative research projects 400 M€
  - ➤ Research Labs and Research Fab Microelectronics Germany 400 M€
- Germany plans participation in IPCEI
  - > 1000 M€ from the Federal Ministry for Economic Affairs and Energy.



### SME survey background

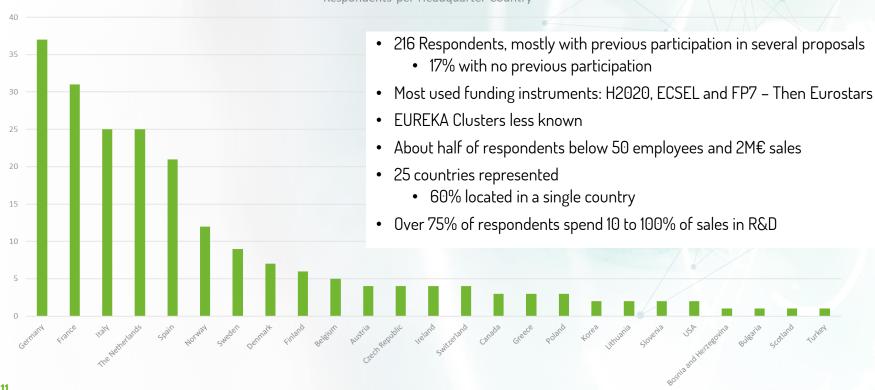


- Initiated early 2018
- Many actors jointly defining and distributing questionnaire
  - Industry associations: AENEAS, ARTEMIS-IA, EPoSS, SEMI
  - Funding programmes and organisations: EC, ECSEL, EUREKA
  - Regional clusters: ARCSIS, DSP Valley, Minalogic, SCS, Silicon Saxony, Systematic
- Online survey took place during Q2 2018

# Typology of Survey Respondents

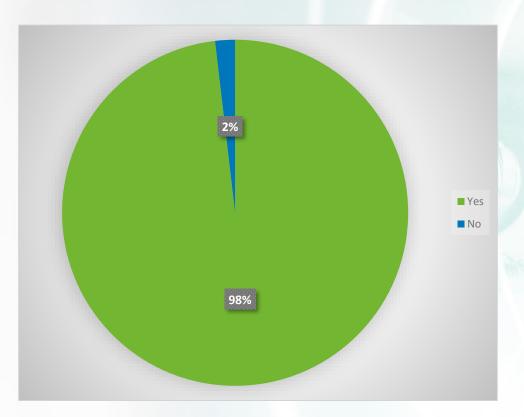


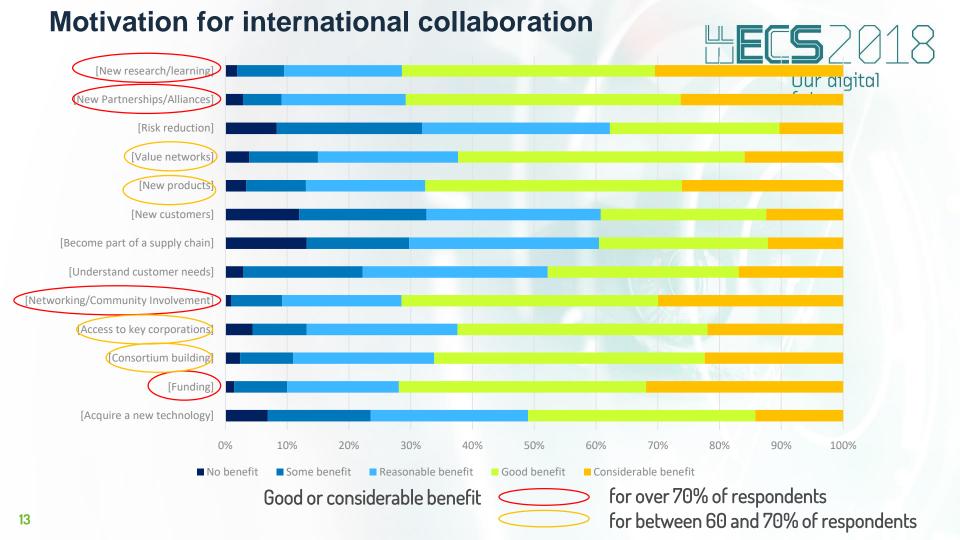
Respondents per Headquarter Country

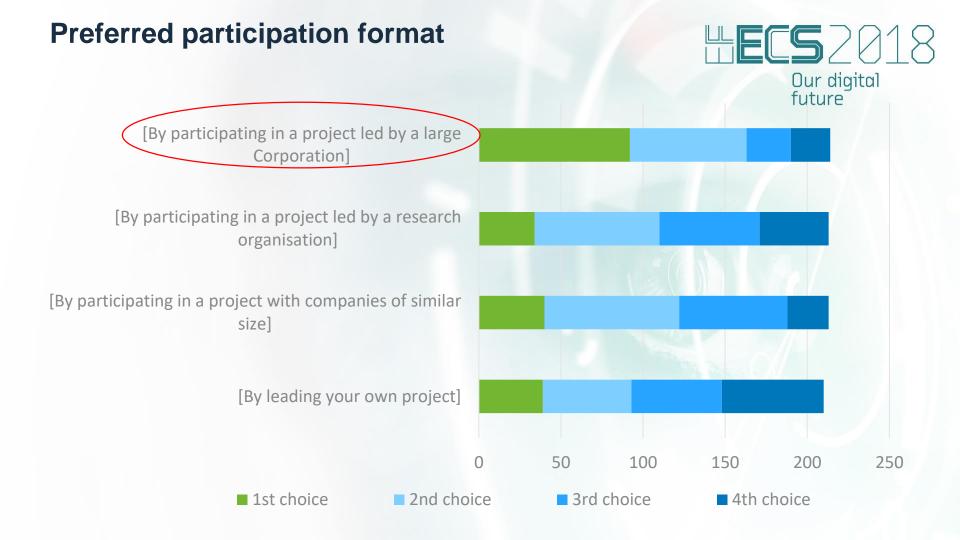


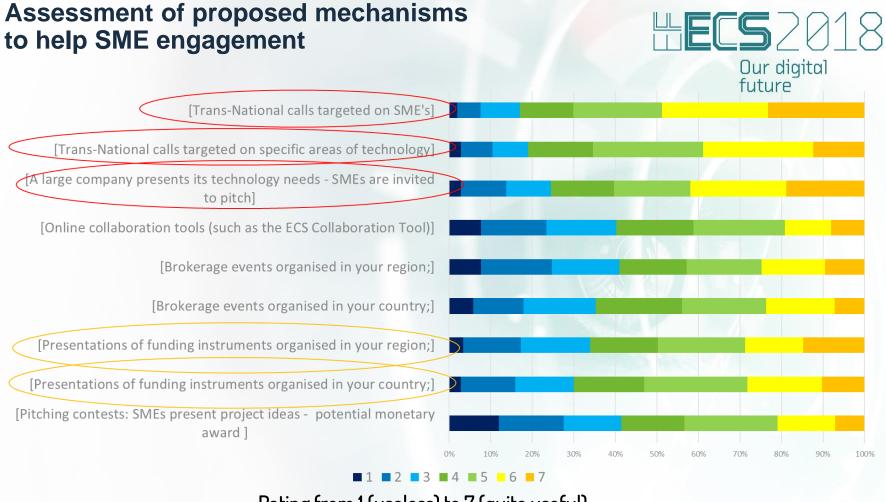
## Do you see potential / benefit from international collaboration? Overwhelmingly "Yes"



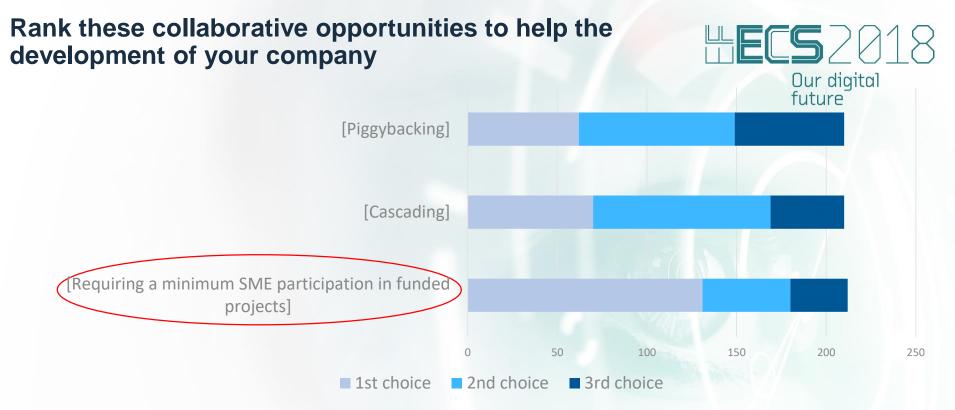








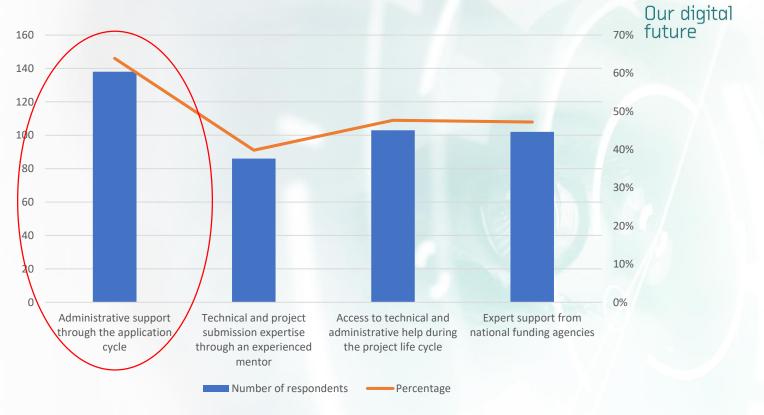
Rating from 1 (useless) to 7 (quite useful)



Cascading: Within a collaborative project, a source of funding is provided funding, with the specific obligation to transfer that funding to SMEs who become involved in the project (the SME is not applying for funding itself)
Piggybacking: SME's can have the option to join a running project to bring additional expertise to the project team. Funding would be provided through a separate national application

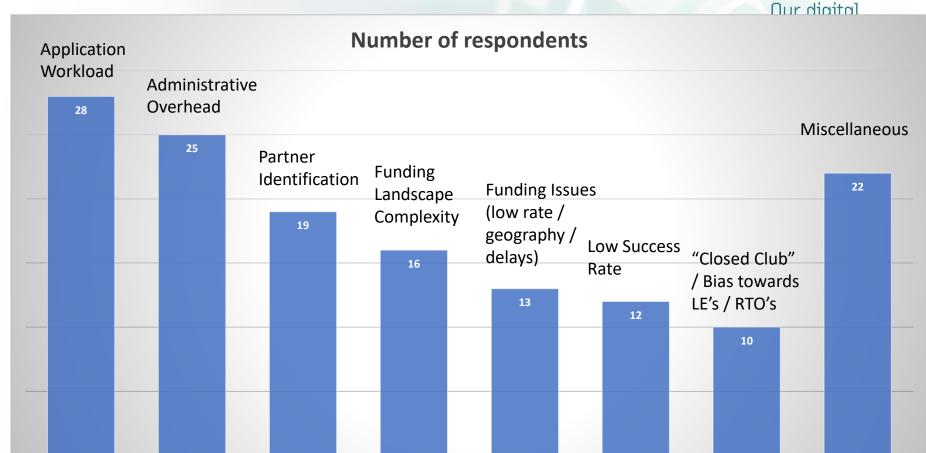
#### What kind of support would you need?





#### **Hurdles to SME participation**





#### **Room for improvement**



Funding instruments design

Funding opportunities knowledge

Proposal elaboration and submission

Consortium Building

